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HARTING SEK 18 male low profile solder and press-in RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. drilled hole $\varnothing$ finished hole $\varnothing$ plating (e.g. Sn) Cu min. 25 μm <table><tr><td rowspan="3">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole $\varnothing$</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 μm</td></tr><tr><td>Sn</td><td>max. 15 μm</td></tr><tr><td rowspan="3">Chemical tin plated PCB</td><td>plated hole $\varnothing$</td><td>0,94 – 1,09 mm</td></tr><tr><td>Drilled hole $\varnothing$</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 μm</td></tr><tr><td rowspan="4">Gold /Nickel plated PCB</td><td>Sn</td><td>min. 0,8μm</td></tr><tr><td>plated hole $\varnothing$</td><td>1,00 – 1,10 mm</td></tr><tr><td>Drilled hole $\varnothing$</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 μm</td></tr><tr><td rowspan="4">Silver plated PCB</td><td>Ni</td><td>3 – 7 μm</td></tr><tr><td>Au</td><td>0,05 – 0,12 μm</td></tr><tr><td>plated hole $\varnothing$</td><td>1,00 – 1,10 mm</td></tr><tr><td>Drilled hole $\varnothing$</td><td>1,15-0,03 mm</td></tr><tr><td rowspan="3">Copper plated PCB (OSP)</td><td>Cu</td><td>min. 25 μm</td></tr><tr><td>plated hole $\varnothing$</td><td>1,00 – 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole $\varnothing$	1,15-0,03 mm	Cu	min. 25 μ m	Sn	max. 15 μ m	Chemical tin plated PCB	plated hole $\varnothing$	0,94 – 1,09 mm	Drilled hole $\varnothing$	1,15-0,03 mm	Cu	min. 25 μ m	Gold /Nickel plated PCB	Sn	min. 0,8 μ m	plated hole $\varnothing$	1,00 – 1,10 mm	Drilled hole $\varnothing$	1,15-0,03 mm	Cu	min. 25 μ m	Silver plated PCB	Ni	3 – 7 μ m	Au	0,05 – 0,12 μ m	plated hole $\varnothing$	1,00 – 1,10 mm	Drilled hole $\varnothing$	1,15-0,03 mm	Copper plated PCB (OSP)	Cu	min. 25 μ m	plated hole $\varnothing$	1,00 – 1,10 mm																																																			
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